POEB4FW

Power over ethernet (PoE)/PD forward transformer



Product features

- Forward topology
- IEEE 802.3xx
- Up to 250 kHz switching frequency
- Input range from 40 V to 60 V
- EFD30 SMT package (36 mm x 33 mm x 14.5 mm)
- 1500 Vac isolation between primary and secondary
- Power level: 156 watts
- · Low leakage inductance
- Ferrite core material
- Moisture sensitivity level (MSL): 1

Applications

- Lighting
- · Industrial automation
- · Security systems
- VoIP phone systems
- · Network and Bluetooth access points
- · Network routers, repeaters
- Uninterruptible power supplies (UPS)
- · Retail point-of-information (POI) systems
- Vending and gaming machines
- · Remote cameras

Environmental compliance and general specifications

- Storage temperature (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)





Product specifications

Part number ³	Output power (W)	OCL¹ (μΗ) ±27%	SCL² (µH) maximum	Turns Ratio Schematic 1: Pri : Sec 1 : Aux ±3%	Output	DCR (mΩ) maximum @ +25 °C (Pri)	DCR (mΩ) maximum @ +25 °C (Sec 1)	DCR (mΩ) maximum @ +25 °C (Aux)	Schematic
POEB4FW1V156W1X12	156	100	0.25	1:0.5:0.5	(1) x 12.0 V @ 13.0 A	20	4.25	250	1

1. Open circuit inductance (OCL) is for the primary, test parameters: 100 kHz, 0.1 V_{mm}, 0.0 Adc, +25 °C

Short circuit inductance (SCL) is for the primary with the other windings shorted, test parameters: 100 kHz, 0.1 V_{ms⁴}

1

12 SURFACES

0.0 Adc, +25 °C

3. Part Number Definition: POEB3FWxVxWxXx

POEB4FW=Product code and size

xVxW, xV=Version indicator, xW= Output power, xXx=number of outputs and output voltage

Mechanical parameters, schematic, pad layout (mm)



Dimension	Value
A	33.02 maximum
В	36.07 maximum
B1	31.6
С	14.0 ± 0.5
D	27.0 typical
E	5.0 ± 0.3
G	0.64 ± 0.1

Part marking: Dot indicates pin 1, POEB4FW = Product code and size, xV=Version indicator, xW= Total output power, xXx=number of outputs and output voltage. wwllyy R= lot code

All pin length doesn't include tin icicles All soldering surfaces to be coplanar within 0.13 millimeters

Tolerances are ±0.25 millimeters unless stated otherwise

Pad layout tolerances are ±0.1 millimeters unless stated otherwise

Traces or vias underneath the transformer is not recommended

Recommended PCB Layout



Schematic



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Value

Packaging information (mm)

Supplied in tape and reel packaging, 13" diameter reel (EIA-481 compliant) 50 parts per reel



SECTION B-B

W ± 0.30	56		
F ± 0.10	26.2		
E1 ± 0.10	1.75		
P0 ± 0.10	4		
P1 ± 0.10	48		
P2 ± 0.15	2		
D0 + 0.10/-0	1.5		
D1 minimum	2		
A0 ± 0.10	31.5		
A1 ref.	27.1		
B0 ± 0.10	37		
B1 ± 0.1	32		
K0 ± 0.10	15		
T ± 0.05	0.5		
T1 maximum	0.1		
T2 maximum	15.7		
SO	52.4		

Dimension

General specifications

Reflow: MIL-STD-202G Condition J, $+245 \text{ °C} \pm 5 \text{ °C}$, 30 s ± 5 s, 1 times reflow

Solderability: J-STD-002. 8 hours steam age test, Flux type: R0L0, Solder: +245 °C \pm 5 °C

Mechanical shock: MIL-STD-202 Method 213. Half-sine shock pulse, peak=100 g's, 6.0 ms, total 18 shocks

Vibration: MIL-STD-202, Method 204. Gravity= 10 g, Frequency= 10 Hz to 55 Hz to 10 Hz, Direction: 3 (X,Y, Z), each 12 cycles, Duration= 20 minutes in each direction

Salt spray: GB/T6461-2002, Salt spray concentration= 5% ± 1%, Test temperature= +35 ± 2 °C, pH value= 6.5 to 7.2, Time= 48 hours, After removing the product, wash in warm water or salted water, then natural air-dried for 1 hour

High temperature storage test: MIL-STD-202G Method 108, +125 °C, Duration= 1000 hours

Temperature cycling: JESD22 Method JA-104, High temperature= +125 °C, low temperature -40 °C, conversion time 30 minutes, 100 cycles.

Biased humidity: MIL-STD-202G Method 103, +85 °C, 85% RH, Duration= 1000 hours.

Life: MIL-STD-202 Method 108, 1000 hours, +85 °C at rated I me (Ambient plus self temperature rise no more than +125 °C)

Solder reflow profile



T_c -5 °C Table 1 - Standard SnPb solder (T_c)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_c)

Package thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Profile feature	Standard SnPb solder	Lead (Pb) free solder	
Preheat and soak • Temperature min. (T _{smin})	100 °C	150 °C	
 Temperature max. (T_{smax}) 	150 °C	200 °C	
• Time (T _{smin} to T _{smax}) (t _s)	60-120 seconds	60-120 seconds	
Ramp up rate TL to Tp	3 °C/ second max.	3 °C/ second max.	
Liquidous temperature (TL) Time (tL) maintained above ${\rm T_L}$	183 °C 60-150 seconds	217 °C 60-150 seconds	
Peak package body temperature (T _P)*	Table 1	Table 2	
Time $(t_p)^*$ within 5 °C of the specified classification temperature (T_c)	10 seconds*	10 seconds*	
Ramp-down rate (T _p to T _L)	6 °C/ second max.	6 °C/ second max.	
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.	

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

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